

Dear DEED Members,

Here is your August 2014 installment of the "All the News InDEED" newsletter.

The intent of this newsletter is to inform the DEED community about upcoming events and related news in DEED, ASEE, and engineering design. The newsletters will be sent on the 15th of every month; submissions are welcome.

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1) DEED Call for Papers

The Design in Engineering Education Division (DEED) invites abstracts for papers to be presented at the 2015 ASEE annual conference to be held June 14-17 in Seattle, Washington.

DEED seeks contributions on topics that include, but are not limited to, capstone design, design for industry/manufacturing, innovation in design education, design instruction and pedagogy, teams and teamwork in design education, design for community, interdisciplinary and multidisciplinary design, use of technology to enhance design education, sustainable design, design for "X", assessment of design activities, design realization, and design methodology.

For questions or ideas concerning DEED topics or sessions, contact the 2015 DEED Program Chair: Reid Bailey (rrbailey@virginia.edu, 1-434-924-6352).

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2) Interdivisional Town Hall Meeting Report (ASEE 2014)

During the ASEE 2014 annual meeting in Indianapolis, the Ad Hoc Committee on Interdivisional Cooperation organized an Interdivisional Town Hall Meeting on the topic of "Why is Change so Difficult to Sustain in Engineering Education?" The event was co-sponsored by 31 ASEE Divisions and Constituent Committees, including DEED. Approximately 70 participants, including over 45 delegates from the divisions were present at the gathering.

The meeting was organized as a highly interactive session devoted to identifying specific challenges and opportunities for pursuing more sustainable reform initiatives, and discussing them through breakout sessions. The focus was on both general solutions as well as solutions specific to particular areas. The discussions from each breakout session were reported to the larger group, collected in electronic form, and distributed for refinement and final distribution to all ASEE Divisions.

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3) New! Capstone Design Community Mailing List

The Capstone Design Community is a network of faculty, administrators, industry representatives, and students active in the capstone engineering design experience.

If you would like to keep up with news and activities, simply join the NEW Capstone Design Community Mailing List - subscribe at the community's new website: capstonedesigncommunity.org.

You can select whether you'd like email related to upcoming capstone design conferences, the capstone design hub development, and/or the capstone design community in general. Join the fun!

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4) Submitting to the InDEED Newsletter

To submit an item to the please prepare a short description (no more than 3 paragraphs) including any relevant URLs and contact info. Email this information to showe@smith.edu. The newsletter will be sent out on the 15th of each month.

Cheers,
Susannah Howe
Chair, ASEE DEED 2014-2015